



<b>File Name</b>	<b>Specification for EE0160AE-1</b>	<b>Module Number</b>	<b>EE0160AE-1</b>
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## Specification for EE0160AE-1 EPD

**Model NO. : EE0160AE-1**

<b>Prepared by</b>	<b>Checked by</b>	<b>Approved by</b>

### Customer approval

<b>Customer</b>	<b>Approved by</b>	<b>Date of approval</b>



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<b>Version</b>	<b>Content</b>	<b>Date</b>	<b>Producer</b>
A/0	New release	2017/04/17	ZHP



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## 1 General Description

EE0160AE-1 is an Active Matrix Electrophoretic Display(AM EPD), with interface and a reference system design. The 1.6 inch active area contains 200x200 pixels. The module is a TFT-array driving electrophoretic display, with integrated circuits including gate driver, source driver, MCU interface, timing controller, oscillator, DC-DC, SRAM, LUT, VCOM. Module can be used in portable electronic devices, such as Electronic Shelf Label (ESL) System.

## 2 Features

- ◆ 200×200 pixels display
- ◆ White reflectance above 30%
- ◆ Contrast ratio above 8:1
- ◆ Ultra wide viewing angle
- ◆ Ultra low power consumption
- ◆ Pure reflective mode
- ◆ Bi-stable display
- ◆ Commercial temperature range
- ◆ Landscape, portrait modes
- ◆ Hard-coat antiglare display surface
- ◆ Ultra Low current deep sleep mode
- ◆ On chip display RAM
- ◆ Waveform stored in On-chip OTP
- ◆ Serial peripheral interface available
- ◆ On-chip oscillator
- ◆ On-chip booster and regulator control for generating VCOM, Gate and Source driving voltage
- ◆ I<sup>2</sup>C signal master interface to read external temperature sensor

## 3 Application

Electronic Shelf Label System

## 4 Mechanical Specification

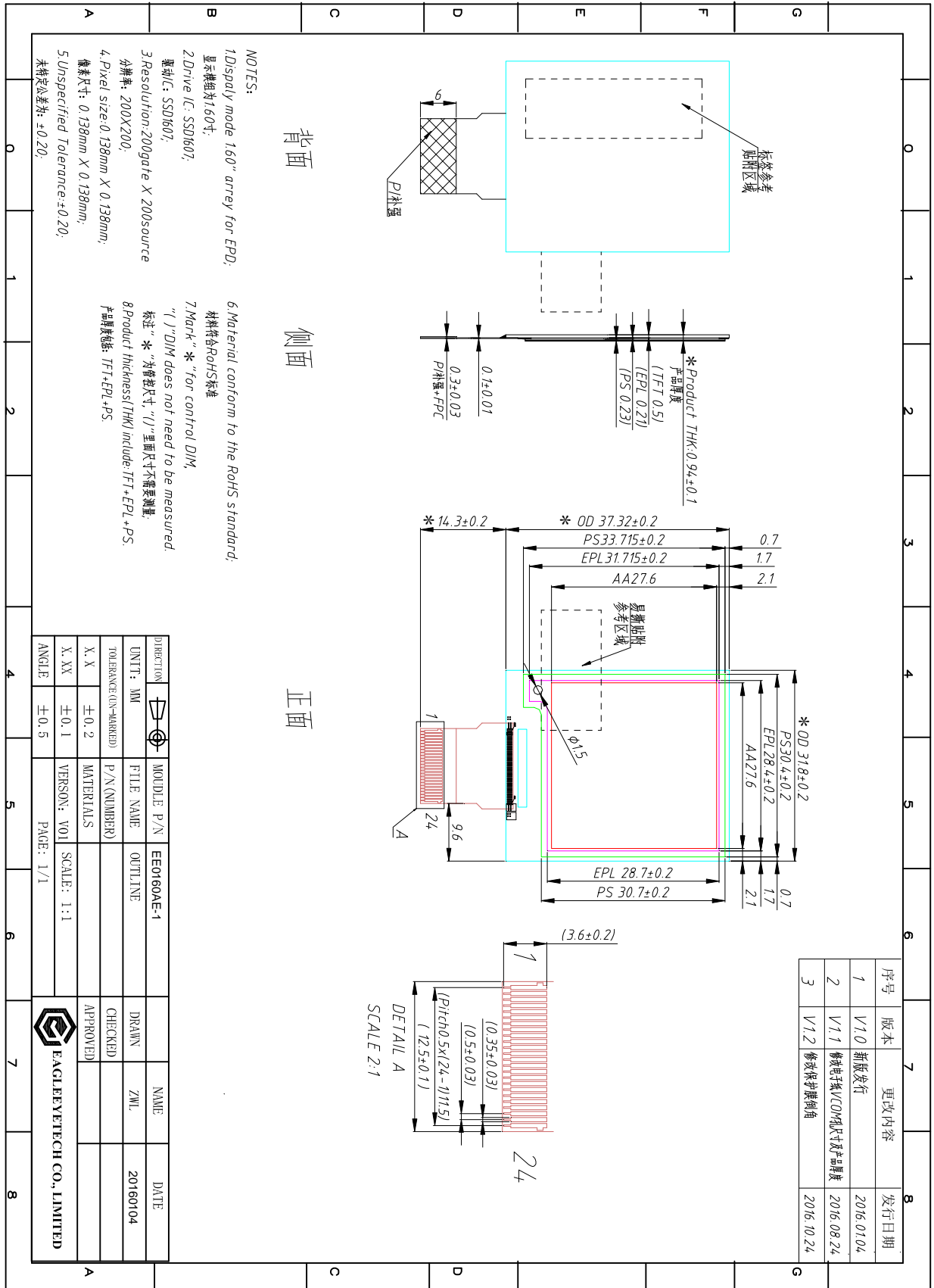
### 4.1 Dimension

Parameter	Specifications	Unit	Remark
Screen Size	1.6	Inch	
Display Resolution	200(H)×200(V)	Pixel	<b>DPI:184</b>
Active Area	27.60×27.60	mm	
Pixel Pitch	0.138×0.138	mm	
Pixel Configuration	Rectangle		
Outline Dimension	31.80(H)×37.2 (V) ×1.05(D)	mm	
Weight	2.7±0.5	g	



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### 4.2 Mechanical Drawing of EPD Module





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## 5 Input/output Pin Assignment

No.	Name	I/O	Description	Remark
1	NC		Do not connect with other NC pins	
2	GDR	O	N-Channel MOSFET Gate Drive Control	
3	RESE	I	Current Sense Input for the Control Loop	
4	VGL	C	Negative Gate driving voltage	
5	VGH	C	Positive Gate driving voltage	
6	TSCL	O	I <sup>2</sup> C Interface to digital temperature sensor Clock pin	
7	TSDA	I/O	I <sup>2</sup> C Interface to digital temperature sensor Data pin	
8	BS1	I	Bus Interface selection pin	Note 5-4
9	BUSY	O	Busy state output pin	Note 5-3
10	RES#	I	Reset signal input. Active Low.	
11	D/C#	I	Data /Command control pin	Note 5-2
12	CS#	I	Chip select input pin	Note 5-1
13	D0	I	Serial Clock pin (SPI)	
14	D1	I	Serial Data pin (SPI)	
15	VDDIO	P	Power Supply for interface logic pins It should be connected with VCI	
16	VCI	P	Power Supply for the chip	
17	VSS	P	Ground	
18	VDD	C	Core logic power pin VDD can be regulated internally from VCI. A capacitor should be connected between VDD and VSS under all circumstances	
19	VPP	P	Power Supply for OTP Programming	
20	VSH	C	Positive Source driving voltage	
21	PREVGH	C	Power Supply pin for VGH and VSH	
22	VSL	C	Negative Source driving voltage	
23	PREVGL	C	Power Supply pin for VCOM, VGL and VSL	
24	VCOM	C	VCOM driving voltage	

I = Input Pin, O =Output Pin, I/O = Bi-directional Pin (Input/Output), P = Power Pin, C = Capacitor Pin



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Note 5-1: This pin is the chip select input connecting to the MCU. The chip is enabled for MCU communication only when CS# is pulled LOW.

Note 5-2: This pin is Data/Command control pin connecting to the MCU in 4-wire SPI mode. When the pin is pulled HIGH, the data at D1 will be interpreted as data. When the pin is pulled LOW, the data at D1 will be interpreted as command.

Note 5-3: This pin is Busy state output pin. When Busy is High, the operation of chip should not be interrupted, command should not be sent, e.g., The chip would put Busy pin High when

- Outputting display waveform
- Programming with OTP
- Communicating with digital temperature sensor

Note 5-4: Bus interface selection pin

<b>BS1 State</b>	<b>MCU Interface</b>
L	4-lines serial peripheral interface(SPI)
H	3- lines serial peripheral interface(SPI) - 9 bits SPI

## 6 Electrical Characteristics

### 6.1 Absolute Maximum Rating

<b>Parameter</b>	<b>Symbol</b>	<b>Rating</b>	<b>Unit</b>
Logic supply voltage	$V_{CI}$	-0.5 to +4.0	V
Logic Input voltage	$V_{IN}$	-0.5 to $V_{CI}+0.5$	V
Logic Output voltage	$V_{OUT}$	-0.5 to $V_{CI}+0.5$	V

Note: Maximum ratings are those values beyond which damages to the device may occur. Functional operation should be restricted to the limits in the Panel DC Characteristics tables.

### 6.2 Panel DC Characteristics

The following specifications apply for:  $V_{SS}=0V$ ,  $V_{CI}=3.0V$ ,  $T_{OPR}=25^{\circ}C$ .

<b>Parameter</b>	<b>Symbol</b>	<b>Condition</b>	<b>Applicable pin</b>	<b>Min.</b>	<b>Typ.</b>	<b>Max.</b>	<b>Unit</b>
Logic supply voltage	$V_{CI}$	-	$V_{CI}$	2.4	3.0	3.6	V
High level input voltage	$V_{IH}$	-	-	$0.8 V_{CI}$	-	-	V
Low level input voltage	$V_{IL}$	-	-	-	-	$0.2 V_{CI}$	V
High level output voltage	$V_{OH}$	$I_{OH} = -100\mu A$	-	$0.9 V_{CI}$	-	-	V
Low level output voltage	$V_{OL}$	$I_{OL} = 100\mu A$	-	-	-	$0.1 V_{CI}$	V
OTP Program voltage	$V_{PP}$	-	$V_{PP}$	-	7.5	-	V
Typical power	$P_{TYP}$	$V_{CI}=3.0V$	-	-	12	30	mW
Deep sleep mode	$P_{STPY}$	$V_{CI}=3.0V$	-	-	0.006	-	mW
Typical operating current	$I_{opr\_VCI}$	$V_{CI}=3.0V$	-	-	4.0	10	mA

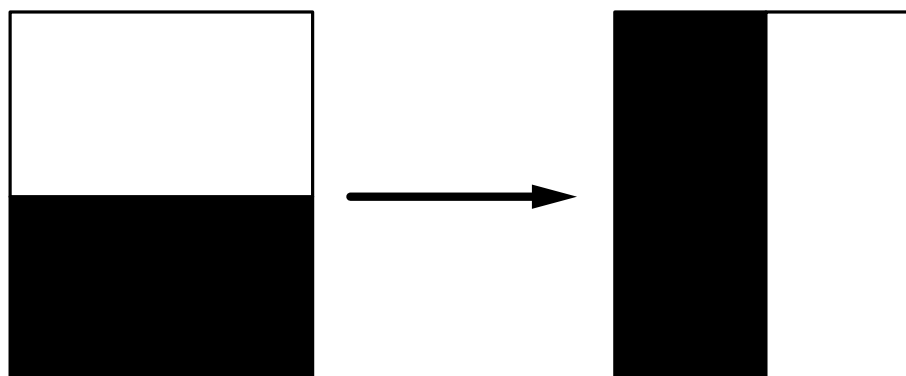




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Sleep mode current	Islp_VCI	VCI=3.0V DC/DC OFF No clock No output load Ram data retain	VCI	-	35	50	uA
Deep sleep mode current	Idslp_VCI	VCI=3.0V DC/DC OFF No clock No output load Ram data not retain	VCI	-	2	5	uA
Operation temperature range	T <sub>OPR</sub>	-	-	0	-	50	°C
Operation relative humidity	RHop	-	-	-	-	70	%RH
Operation illuminance intensity	E	indoor only	-	-	-	2000	lux
Storage temperature range	T <sub>STG</sub>	-	-	-20	-	70	°C
Storage relative humidity	RHst	-	-	30	-	60	%RH

Notes:

- The typical power is measured with following transition from horizontal 2 scale pattern to vertical 2 scale pattern. (Figure 10-2)



**Figure 10-2 The typical power consumption measure pattern**

- The deep sleep power is the consumed power when the panel controller is in deep sleep mode.
- The listed electrical/optical characteristics are only guaranteed under the controller & waveform provided by EETECH.

### 6.3 Panel DC Characteristics(Driver IC Internal Regulators)

The following specifications apply for: VSS=0V, VCI=3.0V, T<sub>OPR</sub> =25°C.

Parameter	Symbol	Condition	Applicable pin	Min.	Typ.	Max.	Unit
VCOM output voltage	VCOM	-	VCOM	-4.0	-	-0.2	V
Positive Source output voltage	V <sub>SH</sub>	-	S <sub>0</sub> ~S <sub>199</sub>	+14.5	+15	+15.5	V
Negative Source output voltage	V <sub>SL</sub>	-	S <sub>0</sub> ~S <sub>199</sub>	-15.5	-15	-14.5	V
Positive gate output voltage	V <sub>gh</sub>	-	G <sub>0</sub> ~G <sub>199</sub>	+21	+22	+23	V
Negative gate output voltage	V <sub>gl</sub>	-	G <sub>0</sub> ~G <sub>199</sub>	-21	-20	-19	V

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## 6.4 Panel AC Characteristics

### 6.4.1 MCU Interface Selection

MCU interface consist of 2 data/command pins and 3 control pins. The pin assignment at different interface mode is summarized in Table 10-4-1. Different MCU mode can be set by hardware selection on BS1 pins. The display panel only supports 4-wire SPI or 3-wire SPI interface mode.

Pin Name	Data/Connnand Interface		Control Signal		
	D1	D0	CS#	D/C#	RES#
BS1=L 4-wire SPI	SDIN	SCLK	CS#	D/C#	RES#
BS1=H 3-wire SPI	SDIN	SCLK	CS#	L	RES#

**Table 10-4-1: MCU interface assignment under different bus interface mode**

### 6.4.2 MCU Serial Interface (4-wire SPI)

The serial interface consists of serial clock SCLK, serial data SDIN, D/C#, CS#. In 4-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN.

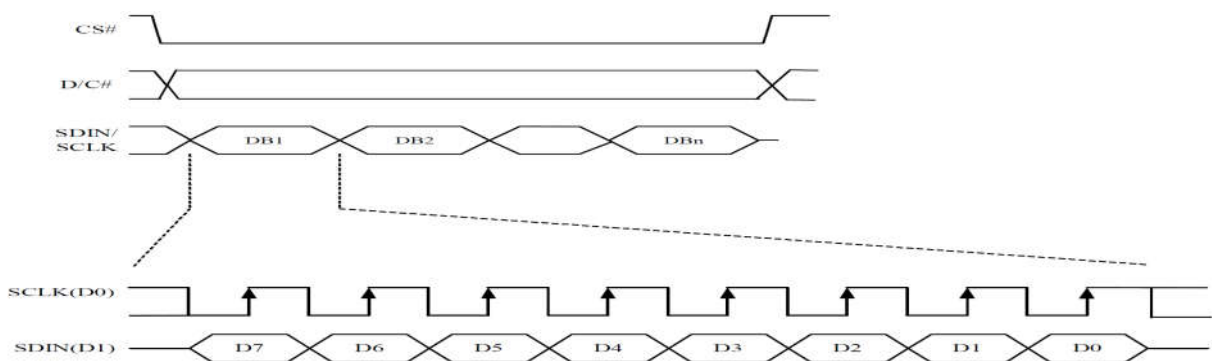
Function	CS#	D/C#	SCLK
Write command	L	L	↑
Write data	L	H	↑

Note: ↑ stands for rising edge of signal

**Table10-4-2: Control pins of 4-wire Serial interface**

SDIN is shifted into an 8-bit shift register on every rising edge of SCLK in the order of D7, D6, ... D0. D/C# is sampled on every eighth clock and the data byte in the shift register is written to the Graphic Display Data RAM (RAM) or command register in the same clock.

Under serial mode, only write operations are allowed.



**Figure 10-4-2: Write procedure in 4-wire SPI mode**

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### 6.4.3 MCU Serial Interface (3-wire SPI)

The 3-wire serial interface consists of serial clock SCLK, serial data SDIN and CS#. In 3-wire SPI mode, D0 acts as SCLK, D1 acts as SDIN.

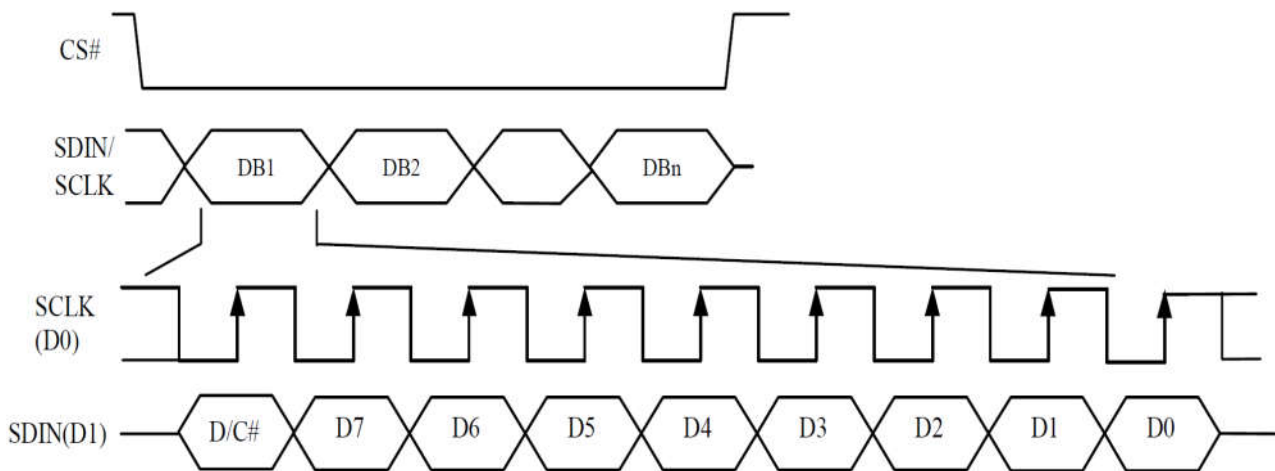
The operation is similar to 4-wire serial interface while D/C# pin is not used. There are altogether 9-bits will be shifted into the shift register on every ninth clock in sequence: D/C# bit, D7 to D0 bit. The D/C# bit (first bit of the sequential data) will determine the following data byte in the shift register is written to the Display Data RAM (D/C# bit = 1) or the command register (D/C# bit = 0).

Under serial mode, only write operations are allowed.

Function	CS#	D/C#	SCLK
Write command	L	Tie	↑
Write data	L	Tie	↑

Note: ↑ stands for rising edge of signal

**Table 10-4-3: Control pins of 3-wire Serial interface**



**Figure 10-4-3: Write procedure in 3-wire SPI mode**

### 6.4.4 Interface Timing

The following specifications apply for: VSS=0V, VCI=3.0V, T<sub>OPR</sub> =25°C.

Symbol	Parameter	Test Condition	Applicable pin	Min.	Typ.	Max.	Unit
Fosc	Internal Oscillator frequency	VCI=2.4 to 3.3V	CL	0.95	1	1.05	MHz



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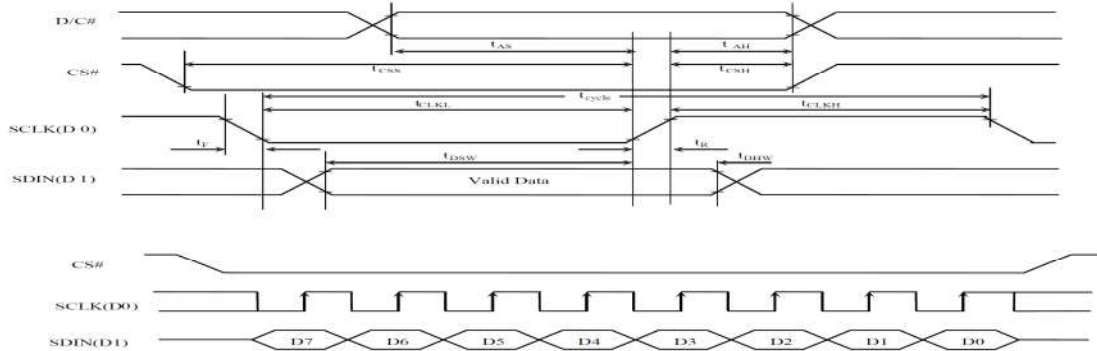


Figure 10-4-4: Serial interface characteristics

( $V_{CI} - V_{SS} = 2.4V$  to  $3.3V$ ,  $T_{OPR} = 25^{\circ}C$ ,  $CL=20pF$ )

Symbol	Parameter	Min.	Typ.	Max.	Unit
$t_{cycle}$	Clock Cycle Time	250	-	-	ns
$t_{AS}$	Address Setup Time	150	-	-	ns
$t_{AH}$	Address Hold Time	150	-	-	ns
$t_{CSS}$	Chip Select Setup Time	120	-	-	ns
$t_{CSH}$	Chip Select Hold Time	60	-	-	ns
$t_{DSW}$	Write Data Setup Time	50	-	-	ns
$t_{DHW}$	Write Data Hold Time	15	-	-	ns
$t_{CLKL}$	Clock Low Time	100	-	-	ns
$t_{CLKH}$	Clock High Time	100	-	-	ns
$t_R$	Rise Time [20% ~ 80%]	-	-	15	ns
$t_F$	Fall Time [20% ~ 80%]	-	-	15	ns

Table 10-4-4: Serial Interface Timing Characteristics

6.4.5 Command Table

R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	01	0	0	0	0	0	0	0	1	Driver Output control	Gate setting Set A[8:0] = 0C7h Set B[2:0] = 0h
0	1		A7	A6	A5	A4	A3	A2	A1	A0		
0	1		0	0	0	0	0	0	0	A8		
0	1		0	0	0	0	0	B2	B1	B0		
0	0	0C	0	0	0	0	1	1	0	0	Booster Soft start Control	Set A[7:0] = CFh Set B[7:0] = CEh Set C[7:0] = 8Dh
0	1		1	A6	A5	A4	A3	A2	A1	A0		
0	1		1	B6	B5	B4	B3	B2	B1	B0		
0	1		1	C6	C5	C4	C3	C2	C1	C0		
0	0	10	0	0	0	1	0	0	0	0	Deep Sleep mode	Deep Sleep mode Control
0	1		0	0	0	0	0	0	0	A0		
											0	Normal Mode [POR]
											1	Enter Deep Sleep Mode



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0	0	11	0	0	0	1	0	0	0	1	Data Entry mode setting	Define data entry sequence $A[1:0] = ID[1:0]$ Address automatic increment / decrement setting The setting of incrementing or decrementing of the address counter can be made independently in each upper and lower bit of the address.  00 –Y decrement, X decrement, 01 –Y decrement, X increment, 10 –Y increment, X decrement, 11 –Y increment, X increment [POR]  $A[2] = AM$ Set the direction in which the address counter is updated automatically after data are written to the RAM.  AM= 0, the address counter is updated in the X direction. [POR] AM = 1, the address counter is updated in the Y direction.
0	1		0	0	0	0	0	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		
0	0	12	0	0	0	1	0	0	1	0	SWRESET	It resets the commands and parameters to their S/W Reset default values except R10h-Deep Sleep Mode Note: RAM are unaffected by this command.



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R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description						
0	0	1A	0	0	0	1	1	0	1	0	Temperature Sensor Control (Write to temperature register)	Write to temperature register. A[7:0] – MSByte 01111111[POR] B[7:0] – LSByte 11110000[POR]						
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>								
0	1		B <sub>7</sub>	B <sub>6</sub>	B <sub>5</sub>	B <sub>4</sub>	0	0	0	0								
0	0	20	0	0	1	0	0	0	0	0	Master Activation	<p>Activate Display Update Sequence</p> <p>The Display Update Sequence Option is located at R22h</p> <p>User should not interrupt this operation to avoid corruption of panel images.</p>						
0	0	21	0	0	1	0	0	0	0	1	Display Update Control 1	<p>Option for Display Update Bypass Option used for Pattern Display, which is used for display the RAM content into the Display</p> <p>OLD RAM Bypass option A [7] A[7] = 1: Enable bypass A[7] = 0: Disable bypass [POR]</p> <p>A[4] value will be used as for bypass. A[4] = 0 [POR]</p> <p>A[1:0] Initial Update Option - Source Control</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <tr> <td>A[1:0]</td> <td>GSC</td> <td>GSD</td> </tr> <tr> <td>01 [POR]</td> <td>GS0</td> <td>GS1</td> </tr> </table>	A[1:0]	GSC	GSD	01 [POR]	GS0	GS1
A[1:0]	GSC	GSD																
01 [POR]	GS0	GS1																
0	1		A <sub>7</sub>	0	0	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>								



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R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description		
0	0	22	0	0	1	0	0	0	1	0	Display Update Control 2	Display Update Sequence Option: Enable the stage for Master Activation		
0	1		A7	A6	A5	A4	A3	A2	A1	A0				Parameter (in Hex)
													Enable Clock Signal, Then Enable Analog Then Load Temperature Sensor Then Load LUT Then INITIAL DISPLAY Then PATTERN DISPLAY Then Disable CP Then Disable OSC	FF [POR]
													Setting for LUT from OTP according to external Temperature Sensor operation 2 Enable Clock Signal, Then Enable Analog Then Load LUT Then PATTERN DISPLAY Then Disable Analog Then Disable OSC	D7
												Setting for LUT from MCU Enable Clock Signal, Then Enable Analog Then PATTERN DISPLAY Then Disable Analog Then Disable OSC	C7	
0	0	24	0	0	1	0	0	1	0	0	Write RAM	After this command, data entries will be written into the RAM until another command is written. Address pointers will advance accordingly.		
0	0	2C	0	0	1	0	1	0	1	1	Write VCOM register	Write VCOM register from MCU interface		
0	1		A7	A6	A5	A4	A3	A2	A1	A0				



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R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description																
0	0	32	0	0	1	1	0	0	1	0	Write LUT register	Write LUT register from MCU [240 bits], (excluding the VSH/VSL and Dummy bit)																
0	1		LUT [30 bytes]																									
0	1																											
0	1																											
...	...																											
0	1																											
0	0	3A	0	0	1	1	1	0	1	0	Set dummy line period	Set A[7:0] = 1Bh																
0	1		0	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>																		
0	0	3B	0	0	1	1	1	0	1	1	Set Gate line width	Set B[3:0] = Bh																
0	1		0	0	0	0	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>																		
0	0	3C	0	0	1	1	1	1	0	0	Border Waveform Control	Select border waveform for VBD																
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	0	0	A <sub>1</sub>	A <sub>0</sub>			<p>A [7] Follow Source at Initial Update Display A [7]=0: [POR] A [7]=1: Follow Source at Initial Update Display for VBD, A [6:0] setting are being overridden at Initial Display STAGE.</p> <p>A [6] Select GS Transition/ Fix Level for VBD A [6]=0: Select GS Transition A[3:0] for VBD A [6]=1: Select FIX level Setting A[5:4] for VBD [POR]</p> <p>A [5:4] Fix Level Setting for VBD</p> <table border="1"> <tr> <td>A[5:4]</td> <td>VBD level</td> </tr> <tr> <td>00</td> <td>VSS</td> </tr> <tr> <td>01</td> <td>VSH</td> </tr> <tr> <td>10</td> <td>VSL</td> </tr> <tr> <td>11[POR]</td> <td>HiZ</td> </tr> </table> <p>A [1:0] GS transition setting for VBD (Select waveform like data A[3:2] to data A[1:0])</p> <table border="1"> <tr> <td>A[1:0]</td> <td>GSA</td> <td>GSB</td> </tr> <tr> <td>01 [POR]</td> <td>GS0</td> <td>GS1</td> </tr> </table>	A[5:4]	VBD level	00	VSS	01	VSH	10	VSL	11[POR]	HiZ	A[1:0]	GSA	GSB	01 [POR]	GS0
A[5:4]	VBD level																											
00	VSS																											
01	VSH																											
10	VSL																											
11[POR]	HiZ																											
A[1:0]	GSA	GSB																										
01 [POR]	GS0	GS1																										





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R/W#	D/C#	Hex	D7	D6	D5	D4	D3	D2	D1	D0	Command	Description
0	0	44	0	1	0	0	0	1	0	0	Set RAM X - address Start / End position	Specify the start/end positions of the window address in the X direction by an address unit  A[4:0]: XSA[4:0], XStart, POR = 00h B[4:0]: XEA[4:0], XEnd, POR = 1Dh
0	1		0	0	0	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		
0	1		0	0	0	B <sub>4</sub>	B <sub>3</sub>	B <sub>2</sub>	B <sub>1</sub>	B <sub>0</sub>		
0	0	45	0	1	0	0	0	1	0	1	Set Ram Y- address Start / End position	Specify the start/end positions of the window address in the Y direction by an address unit  A[8:0]: YSA[8:0], YStart, POR = 000h B[8:0]: YEA[8:0], YEnd, POR = 13Fh
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		
0	1		0	0	0	0	0	0	0	A <sub>8</sub>		
0	1		B <sub>7</sub>	B <sub>6</sub>	B <sub>5</sub>	B <sub>4</sub>	B <sub>3</sub>	B <sub>2</sub>	B <sub>1</sub>	B <sub>0</sub>		
0	1		0	0	0	0	0	0	0	B <sub>8</sub>		
0	0	4E	0	1	0	0	1	1	1	0	Set RAM X address counter	Make initial settings for the RAM X address in the address counter (AC) A[4:0]: XAD[4:0], POR is 00h
0	1		0	0	0	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		
0	0	4F	0	1	0	0	1	1	1	1	Set RAM Y address counter	Make initial settings for the RAM Y address in the address counter (AC) A[8:0]: YAD8:0], POR is 000h
0	1		A <sub>7</sub>	A <sub>6</sub>	A <sub>5</sub>	A <sub>4</sub>	A <sub>3</sub>	A <sub>2</sub>	A <sub>1</sub>	A <sub>0</sub>		
0	1		0	0	0	0	0	0	0	A <sub>8</sub>		
0	1	FF	1	1	1	1	1	1	1	1	NOP	This command is an empty command; it does not have any effect on the display module. However it can be used to terminate Frame Memory Write or Read Commands.

## 7 Optical Specification

Measurements are made with that the illumination is under an angle of 45 degrees, the detection is perpendicular unless otherwise specified.

Symbol	Parameter	Conditions	Values			Units	Notes
			Min.	Typ.	Max		
R	White Reflectivity	White	30	35	-	%	11-1
CR	Contrast Ratio		8:1	9:1	-	-	11-2
2MIN $\Delta$ L	Reduce		-	$\leq 3.5$	-	-	-
T <sub>update</sub>	Image update time	at 25 °C	-	2100	-	ms	-

Notes: 11-1. Luminance meter: Eye-One Pro Spectrophotometer.

11-2. CR=Surface Reflectance with all white pixel/Surface Reflectance with all black pixels.



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## 8 Handling, Safety, and Environment Requirements

### Warning

The display glass may break when it is dropped or bumped on a hard surface. Handle with care. Should the display break, do not touch the electrophoretic material. In case of contact with electrophoretic material, wash with water and soap.

### Caution

The display module should not be exposed to harmful gases, such as acid and alkali gases, which corrode electronic components. Disassembling the display module.

Disassembling the display module can cause permanent damage and invalidates the warranty agreements.

Observe general precautions that are common to handling delicate electronic components. The glass can break and front surfaces can easily be damaged. Moreover the display is sensitive to static electricality and other rough environmental conditions.

### Data sheet status

Product specification

This data sheet contains final product specifications.

### Limiting values

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

### Application information

Where application information is given, it is advisory and does not form part of the specification.



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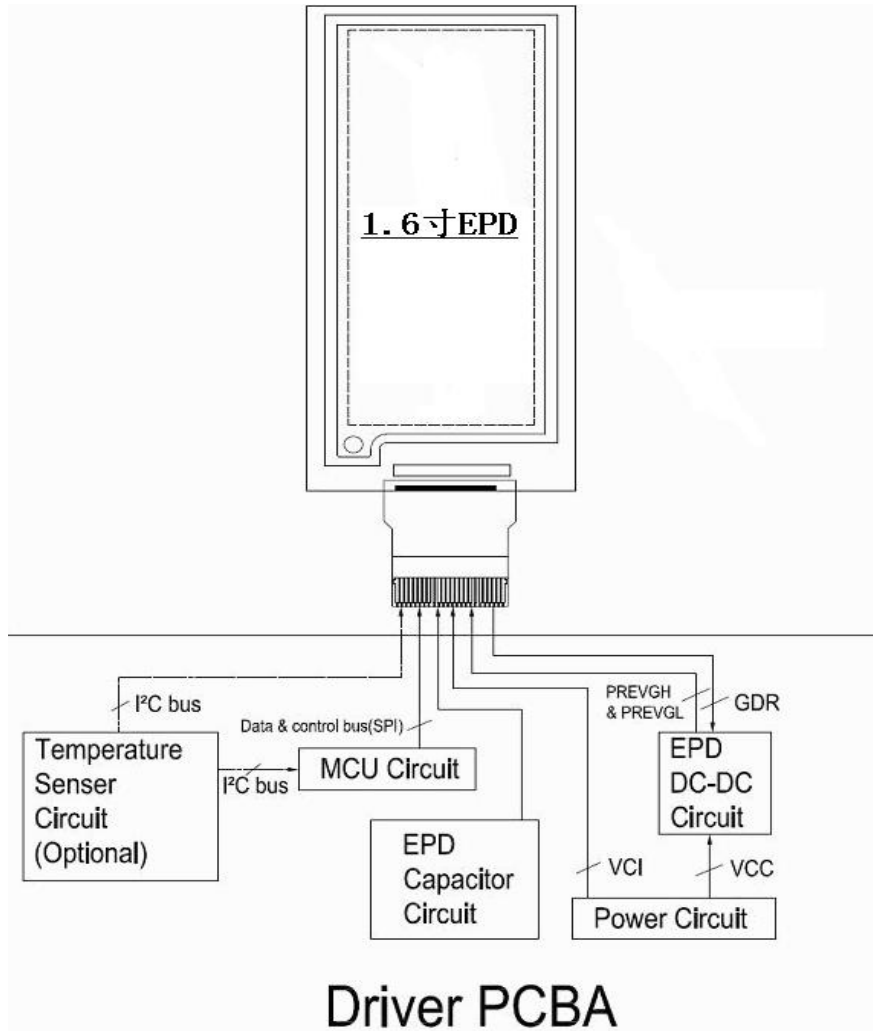
## 9 Reliability Test

No.	Test	Condition	Method	Remark
1	High-Temperature Operation	T = +50°C, RH = 30% for 240 hrs	IEC 60 068-2-2Bp	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
2	Low-Temperature Operation	T = 0°C for 240 hrs	IEC 60 068-2-2Ab	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
3	High-Temperature Storage	T = +70°C, RH=23% for 240 hrs	IEC 60 068-2-2Bp	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
4	Low-Temperature Storage	T = -25°C for 240 hrs	IEC 60 068-2-1Ab	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
5	High-Temperature, High-Humidity Operation	T = +40°C, RH = 90% for 168 hrs	IEC 60 068-2-3CA	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
6	High Temperature, High-Humidity Storage	T = +60°C, RH=80% for 240hrs	IEC 60 068-2-3CA	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
7	Thermal Shock	1 cycle:[-25°C 30min]→[+70 °C 30 min] : 100 cycles	IEC 60 068-2-14	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
8	Package Vibration	1.04G, Frequency: 10~500Hz Direction: X,Y,Z Duration: 1 hours in each direction	Full packed for shipment	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
9	Package Drop Impact	Drop from height of 122 cm on concrete surface. Drop sequence: 1 corner, 3edges, 6 faces One drop for each	Full packed for shipment	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.
10	Electrostatic Effect (non-operating)	Machine model +/- 250V, 0Ω, 200pF	IEC 62179, IEC 62180	At the end of the test, electrical, mechanical, and optical specifications shall be satisfied.



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## 10 Block Diagram

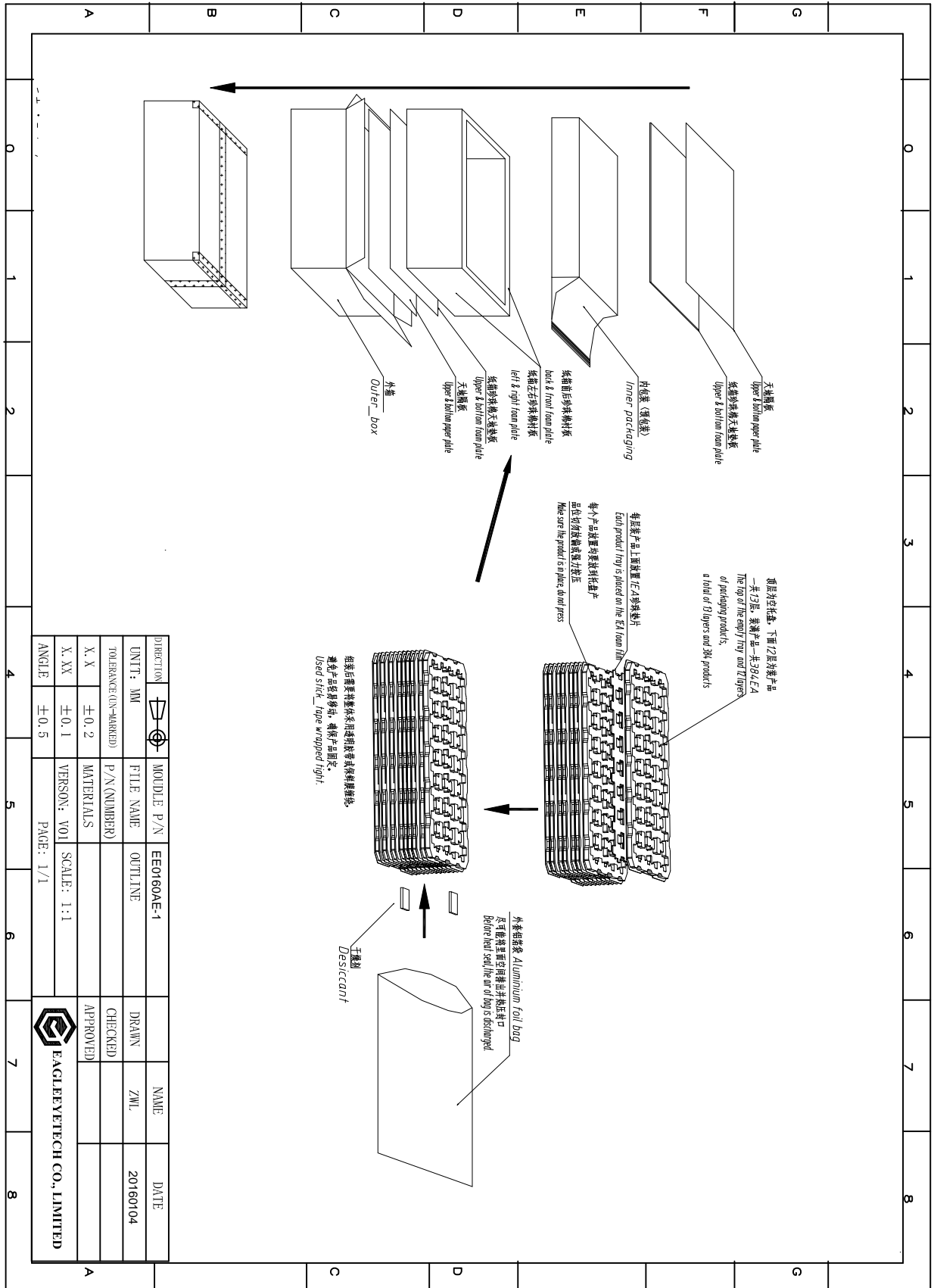






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## 12 Packaging

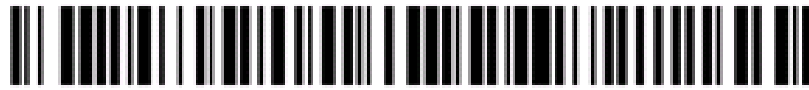




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### 13 Mark and Bar Code Definition

EE0160AE-1      MMMMMMMM



P3C011AP0100001

**(A) EE0160AE-1: Module No.**

**(B) MMMMMMMM: Product date    year month day**

**(C) Bar Code definition**

P3C011 A P 01 00001

(1)    (2) (3)    (4)    (5)

(1) O-Paper Film LOT

(2) Factory

(3) NULL

(4) Product LOT

(5) Product Serial Number